

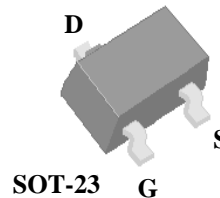
XP2302GN-HF

Halogen-Free Product

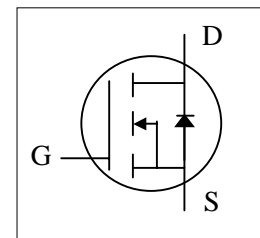


*N-CHANNEL ENHANCEMENT MODE
POWER MOSFET*

- ▼ Capable of 2.5V Gate Drive
- ▼ Small Package Outline
- ▼ Surface Mount Package
- ▼ RoHS Compliant



BV_{DSS}	20V
$R_{DS(ON)}$	85m Ω
I_D	3.2A



Description

XP2302 series are innovative design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The special design SOT-23 package with good thermal performance is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for voltage conversion or switch applications.

Absolute Maximum Ratings @ $T_J=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^\circ\text{C}$	Drain Current ³ , V_{GS} @ 4.5V	3.2	A
$I_D @ T_A=70^\circ\text{C}$	Drain Current ³ , V_{GS} @ 4.5V	2.6	A
I_{DM}	Pulsed Drain Current ¹	10	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	1.38	W
	Linear Derating Factor	0.01	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	90	$^\circ\text{C}/\text{W}$

Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	-	0.1	-	$\text{V}/^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V, I_D=3.6A$	-	-	85	$\text{m}\Omega$
		$V_{GS}=2.5V, I_D=3.1A$	-	-	115	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	-	1.2	V
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=3.6A$	-	6	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
	Drain-Source Leakage Current ($T_j=70^{\circ}\text{C}$)	$V_{DS}=20V, V_{GS}=0V$	-	-	10	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_D=3.6A$	-	4.4	-	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=10V$	-	0.6	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	1.9	-	nC
$t_{d(on)}$	Turn-on Delay Time ²	$V_{DS}=10V$	-	5.2	-	ns
t_r	Rise Time	$I_D=3.6A$	-	37	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=6\Omega$	-	15	-	ns
t_f	Fall Time	$V_{GS}=5V$	-	5.7	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	145	-	pF
C_{oss}	Output Capacitance	$V_{DS}=10V$	-	100	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	50	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	5.3	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current (Body Diode)	$V_D=V_G=0V, V_S=1.2V$	-	-	1	A
I_{SM}	Pulsed Source Current (Body Diode) ¹		-	-	10	A
V_{SD}	Forward On Voltage ²	$I_S=1.6A, V_{GS}=0V$	-	-	1.2	V

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in^2 copper pad of FR4 board, $t \leq 10\text{s}$; $270^{\circ}\text{C}/\text{W}$ when mounted on min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT

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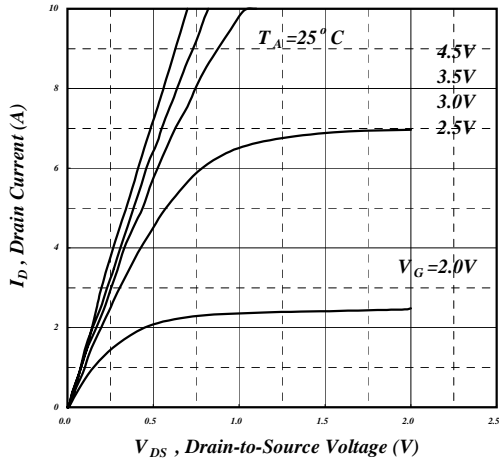


Fig 1. Typical Output Characteristics

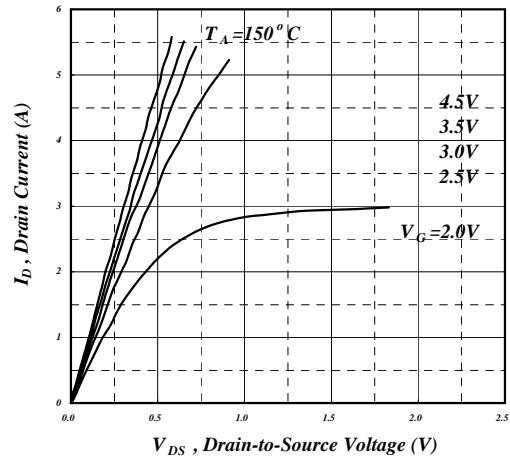


Fig 2. Typical Output Characteristics

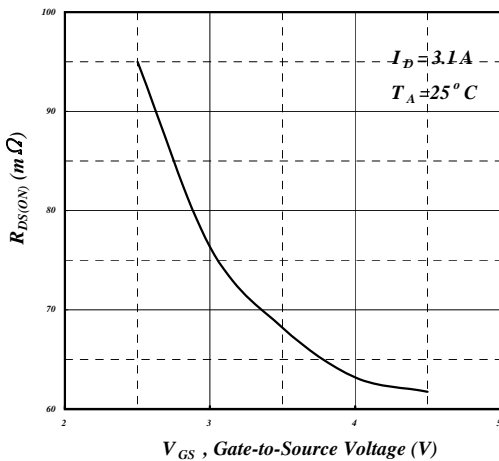


Fig 3. On-Resistance v.s. Gate Voltage

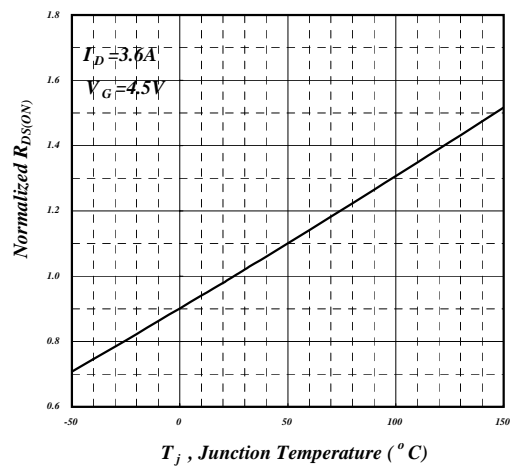


Fig 4. Normalized On-Resistance

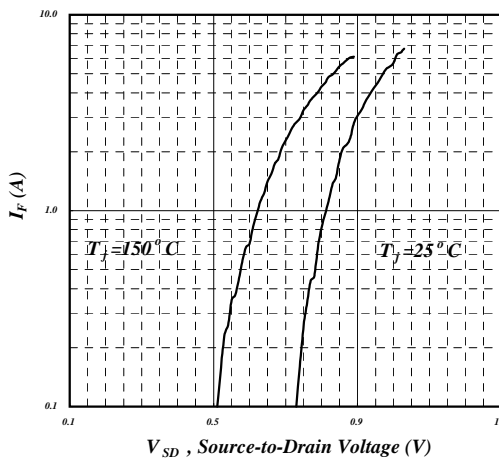


Fig 5. Forward Characteristic of Reverse Diode

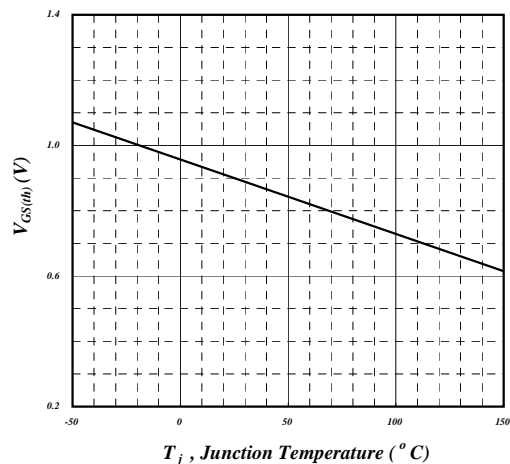


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

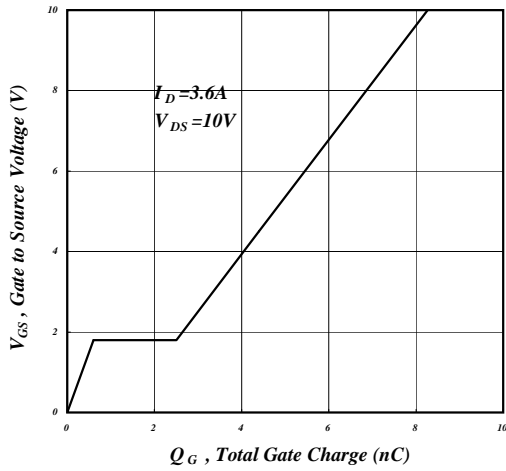


Fig 7. Gate Charge Characteristics

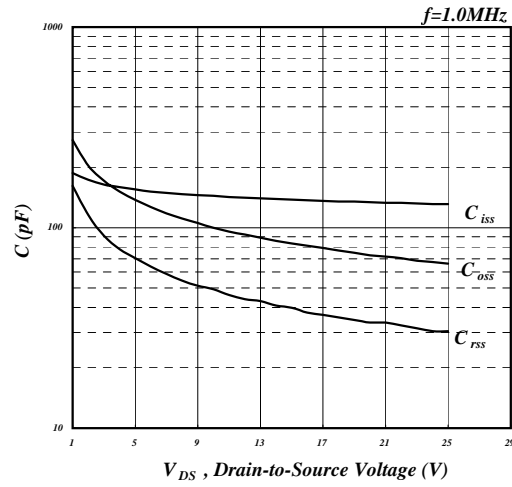


Fig 8. Typical Capacitance Characteristics

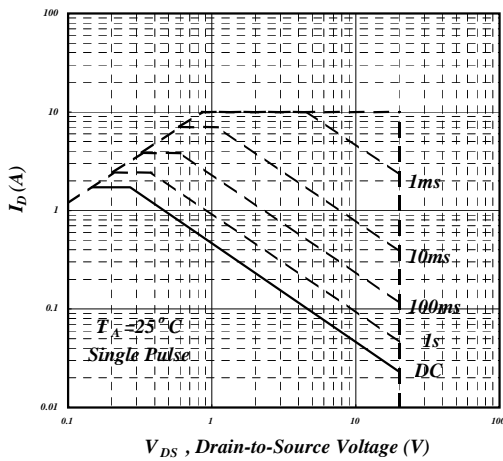


Fig 9. Maximum Safe Operating Area

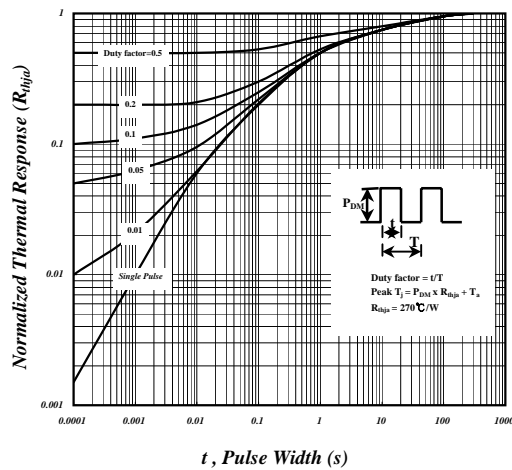


Fig 10. Effective Transient Thermal Impedance

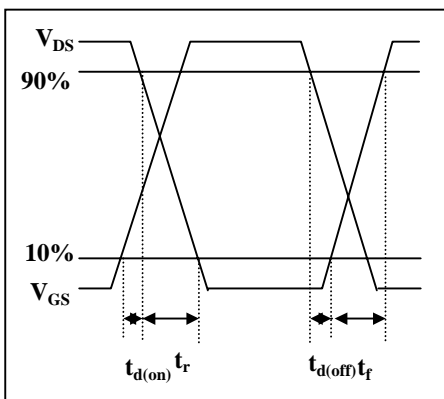


Fig 11. Switching Time Waveform

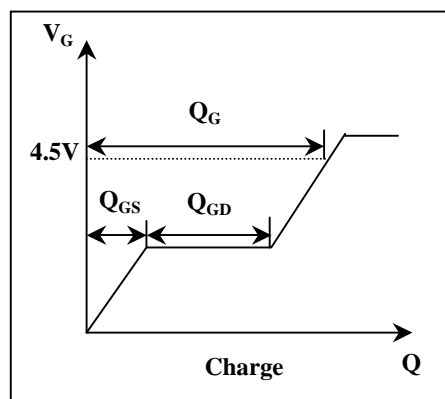


Fig 12. Gate Charge Waveform